

03-07-2002

MD
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ASSIGN



SHEET

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102005248

To: Honorable Commissioner of Patents and Trademarks:

Please record the attached original document(s) or copy thereof.

- 1. Name of conveying party(ies)
 - a) Nikhil V. KELKAR
 - b) Jaime A. BAYAN
- 2. Name and address of receiving party(ies):
 - a) Name: National Semiconductor Corporation
 - Address: 2900 Semiconductor Drive
Santa Clara, CA 95052

APR - 4 2002

- 3. Nature of conveyance

<input type="checkbox"/> Assignment	<input type="checkbox"/> Merger
<input type="checkbox"/> Security Agreement	<input type="checkbox"/> Change of Name
<input checked="" type="checkbox"/> Other: Correction of State of Incorporation of Assignment recorded at Reel 8942 and Frame 0949 on 12/24/1997	<input type="checkbox"/> License Agreement

Execution Date: November 20, 1997 (a) and December 10, 1997 (b)

- 4. Application Number(s) or Patent Number(s): 6,001,723

The title of the (new) application is:

**APPLICATION OF WIRE BOND LOOP AS INTEGRATED
CIRCUIT COMPONENT INTERCONNECT**

- 5. Please send all correspondence concerning this (these) documents to:

Customer Number: 022434

- 6. Total number of applications and patents involved: 1
- 7. Total fee (37 CFR 3.41): \$40.00

- Enclosed
- Any additional fees are authorized to be charged to Deposit Account No. 500388
(Order No. NSC1P103)

8. To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Date: February 28, 2002

Steve D Beyer

Steve D Beyer
Registration No. 31,234

(
03/06/2002 TDIAZ1 00000196 6001723
01 FC:581 40.00 *)*

02-12-1998
100631591

12.24.97

12/21/97
08/998442
J. 300 U.S. PTO

REGISTRATION COVER SHEET
-PATENTS ONLY-

To: Honorable Commissioner of Patents and Trademarks:

Please record the attached original document(s) or copy thereof.

- 1. Name of conveying party(ies)
 - a) Nikhil V. Kelkar
 - b) Jaime A. Bayan
- 2. Name and address of receiving party(ies):
 - a) Name: National Semiconductor Corporation
 - Address: 2900 Semiconductor Drive
Santa Clara, CA 95052-8090
- 3. Nature of conveyance

<input checked="" type="checkbox"/> Assignment	<input type="checkbox"/> Merger
<input type="checkbox"/> Security Agreement	<input type="checkbox"/> Change of Name
<input type="checkbox"/> Other _____	<input type="checkbox"/> License Agreement

Execution Date: November 20, 1997

- 4. Application Number(s) or Patent Number(s): Unassigned

The title of the (new) application is:

**APPLICATION OF WIRE BOND LOOP AS INTEGRATED CIRCUIT PACKAGE
COMPONENT INTERCONNECT**

02/10/1998 TRADE 000000 08998442 all correspondence concerning this (these) documents to:
03 FC:581 40.00 CP

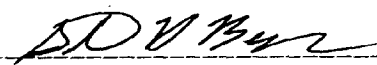
Steve D Beyer
BEYER & WEAVER, LLP
P.O. Box 51147
Palo Alto, CA 94303
Tel. No.: (650) 493-2100
Fax No.: (650) 493-2102

- 6. Total number of applications and patents involved: 1
- 7. Total fee (37 CFR 3.41): \$40.00

- Enclosed
- Authorized to be charged to Deposit Account No. 08-2120
(Order No. _____)

8. To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Date: December 24, 1997


Steve D Beyer
Registration No. 31,234

ASSIGNMENT OF PATENT APPLICATION

(Accompanying Application)

Whereas I/we the undersigned inventor(s) have invented certain new and useful improvements as set for in the patent application entitled:

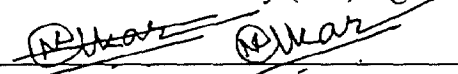
APPLICATION OF WIRE BOND LOOP AS INTEGRATED CIRCUIT COMPONENT INTERCONNECT

(Atty. Docket No.: NSC1P103) for which I (we) have executed an application for a United States Letters Patent.

For good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, I/We the undersigned inventor(s) hereby:

- 1) ^{Delaware 2/20/02} Sell(s), assign(s) and transfer(s) to National Semiconductor Corporation, a ~~California~~ corporation having a place of business at 2900 Semiconductor Drive, Santa Clara, California, (hereinafter referred to as "ASSIGNEE"), the entire right title and interest in any and all improvements and inventions disclosed in, application(s) based upon, and Patent(s) (including foreign patents) granted upon the information which is disclosed in the above referenced application.
- 2) Authorize and request the Commissioner of Patents to issue any and all Letters Patents resulting from said application or any division(s), continuation(s), substitutes(s) or reissue(s) thereof to the ASSIGNEE.
- 3) Agree to execute all papers and documents and, entirely at the ASSIGNEE's expense, perform any acts which are reasonably necessary in connection with the prosecution of said application, as well as any derivative and applications thereof, foreign applications based thereon, and/or the enforcement of patents resulting from such applications.
- 4) Agree that the terms, covenants and conditions of this assignment shall inure to the benefit of the Assignee, its successors, assigns and other legal representative, and shall be binding upon the inventor(s), as well as the inventor's heirs, legal representatives and assigns.
- 5) Warrant and represent that I/we have not entered, and will not enter into any assignment, contract, or understanding that conflicts with this assignment.

Signed on the date(s) indicated beside my (our) signature(s).

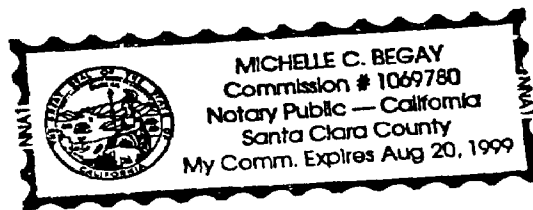
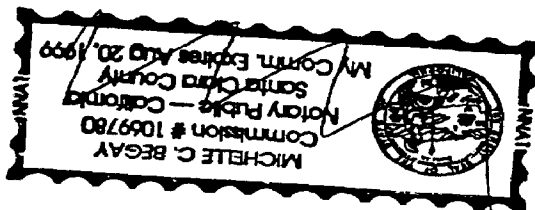
1) Signature:  Date: 11/20/97
Typed Name: Nikhil V. Kelkar

On this 20th day of November, in the year 1997, before me, Michelle C. Begay, personally appeared Nikhil V. Kelkar, personally known to me (or proved to me on the basis of satisfactory evidence) to be the person whose name is subscribed to the within instrument, and acknowledged to me that he/she executed the same in his/her authorized capacity(ies), and that by his/her signature on the instrument the person, or the entity upon behalf of which the person acted, executed the instrument.

WITNESS my hand and official seal.

Signature 

(SEAL)



2) Signature: Jaime A. Bayan
Typed Name: Jaime A. Bayan

Date: 12/10/97

On this 10th day of December, in the year 1997, before me, Michelle C. Begay, personally appeared Jaime A. Bayan, personally known to me (or proved to me on the basis of satisfactory evidence) to be the person whose name is subscribed to the within instrument, and acknowledged to me that he/she executed the same in his/her authorized capacity(ies), and that by his/her signature on the instrument the person, or the entity upon behalf of which the person acted, executed the instrument.

WITNESS my hand and official seal.

Signature Michelle C. Begay

(SEAL)



ASSIGNMENT OF PATENT APPLICATION

(Accompanying Application)

Whereas I/we the undersigned inventor(s) have invented certain new and useful improvements as set for in the patent application entitled:

APPLICATION OF WIRE BOND LOOP AS INTEGRATED CIRCUIT COMPONENT INTERCONNECT

(Atty. Docket No.: NSC1P103) for which I (we) have executed an application for a United States Letters Patent.

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- 1) Sell(s), assign(s) and transfer(s) to National Semiconductor Corporation, a California corporation having a place of business at 2900 Semiconductor Drive, Santa Clara, California, (hereinafter referred to as "ASSIGNEE"), the entire right title and interest in any and all improvements and inventions disclosed in, application(s) based upon, and Patent(s) (including foreign patents) granted upon the information which is disclosed in the above referenced application.
- 2) Authorize and request the Commissioner of Patents to issue any and all Letters Patents resulting from said application or any division(s), continuation(s), substitutes(s) or reissue(s) thereof to the ASSIGNEE.
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- 4) Agree that the terms, covenants and conditions of this assignment shall inure to the benefit of the Assignee, its successors, assigns and other legal representative, and shall be binding upon the inventor(s), as well as the inventor's heirs, legal representatives and assigns.
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Signed on the date(s) indicated beside my (our) signature(s).

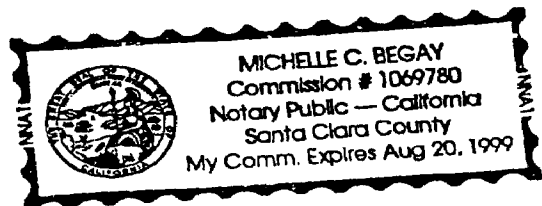
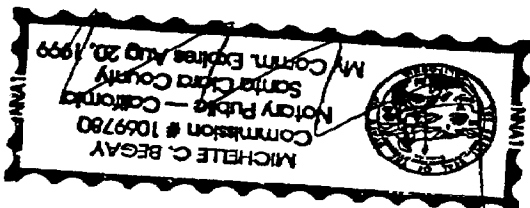
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WITNESS my hand and official seal.

Signature 

(SEAL)



2) Signature: Jaime A. Bayan
Typed Name: Jaime A. Bayan

Date: 12/10/97

On this 10th day of December, in the year 1997, before me, Michelle C. Begay, personally appeared Jaime A. Bayan, personally known to me (or proved to me on the basis of satisfactory evidence) to be the person whose name is subscribed to the within instrument, and acknowledged to me that he/she executed the same in his/her authorized capacity(ies), and that by his/her signature on the instrument the person, or the entity upon behalf of which the person acted, executed the instrument.

WITNESS my hand and official seal.

Signature Michelle C. Begay

(SEAL)

